

## Factory Prog. 4 Output CMOS Oscillator Applications

Series **CCE4C**

- Full Custom Multi-Frequency Programmable Osc
- Reduced EMI by turning off unused output
- Factory Programmable
- Industry-standard packaging saves on board space
- Mult. outputs 1 pkg vs. mult. osc & assoc. comp.
- Lower system cost
- Increased Integration

- High-end multimedia
- Communications
- Industrial
- A/D converters
- Consumer Applications
- Product differentiation
- Low-power applications



Part Numbering Example: **CCE4C 1A 200.0 / 150.0 / 125.0 / 100.0**

<b>CCE4C</b>	<b>1A</b>	<b>200</b>	<b>150</b>	<b>125</b>	<b>100</b>
<b>SERIES</b>	<b>PACKAGE STYLE</b>	<b>FREQUENCY A</b>	<b>FREQUENCY B</b>	<b>FREQUENCY C</b>	<b>FREQUENCY D</b>
	1A=14 pin dip 9=9.6x11.4 SMD	0.2 - 200 MHz	0.2 - 200 MHz	0.2 - 200 MHz	0.2 - 200 MHz

Specifications:	Min	Typ	Max	Unit
<b>Frequency Range:</b>				
Output A CMOS	0.2		200	MHz
Output B CMOS	0.2		200	MHz
Output C CMOS	0.2		200	MHz
Output D CMOS	0.2		200	MHz
<b>Available Stability Options:</b>	-50		50	ppm
<b>Supply Voltage:</b>	3.135	3.3	3.465	V
<b>Operating Temperature Range Options:</b>	-40		85	°C
<b>Storage Temperature:</b>	-55		125	°C
<b>Duty Cycle:</b>	40 45		60 55	% %
<b>Start-Up Time:</b>		3	10	mS
<b>Aging (PPM/1st Year):</b> Ta=25C, Vdd=3.3V			±5	
<b>Static Discharge Voltage</b> Mil-Std 883, method 3015	2000			V
<b>Output Load:</b> CMOS, < 40 MHz CMOS, ≥ 40 MHz			30 15	pF pF
<b>Output Level:</b>	CMOS			
<b>Packaging:</b>	25 / Tube Tape & Reel			14 pin SMD

Notes: Recommended .01 µF bypass capacitor from Vcc to GND. Capacitor should be as close to oscillator as possible.



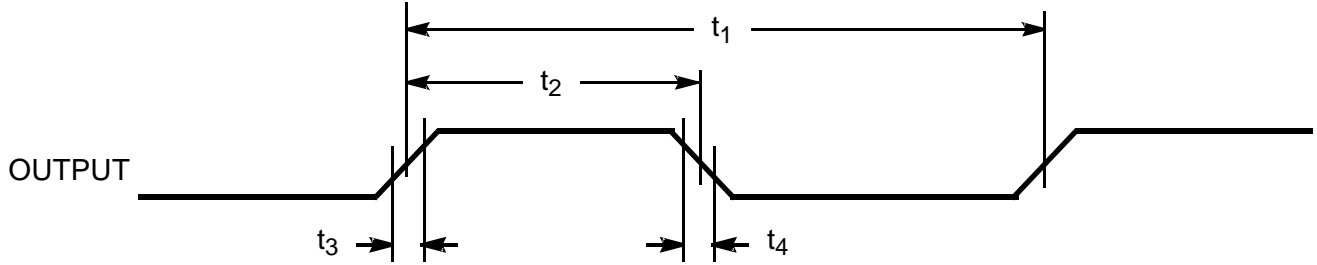
**Electrical Characteristics**

DESCRIPTION		CONDITIONS	MIN	TYP	MAX	UNIT
I <sub>oh</sub>	Output High Current	V <sub>oh</sub> = (L)V <sub>dd</sub> - 0.5, (L)V <sub>dd</sub> = 3.3 V	12	24		mA
I <sub>ol</sub>	Output Low Current	V <sub>ol</sub> = .5, (L)V <sub>dd</sub> = 3.3 V	12	24		mA
V <sub>ih</sub>	High Level Input Voltage	CMOS levels, % of V <sub>dd</sub>	0.7			V
V <sub>il</sub>	Low-Level Input Voltage	CMOS levels, % of V <sub>dd</sub>			0.3	V
I <sub>ih</sub>	Input High Current	V <sub>in</sub> = AV <sub>dd</sub> - 0.3 V		<1	10	μA
I <sub>il</sub>	Input Low Current	V <sub>in</sub> = + 0.3 V		<1	10	μA
I <sub>oz</sub>	Output Leakage Current	tri-state outputs			10	μA
I <sub>dd</sub>	Total Power Supply Current	Example 1: 1 output@19.44 MHz; 1 output@38.88 MHz 1 output@77.76 Mhz; 1 output@155.52 MHz Example 2: 1 output@50 MHz; 1 output@106.25 MHz 1 output@200 Mhz; 1 output@155.52 MHz		26  38		mA  mA
I <sub>dds</sub>	Shutdown Power Supply Curr	Shutdown active		5	20	μA

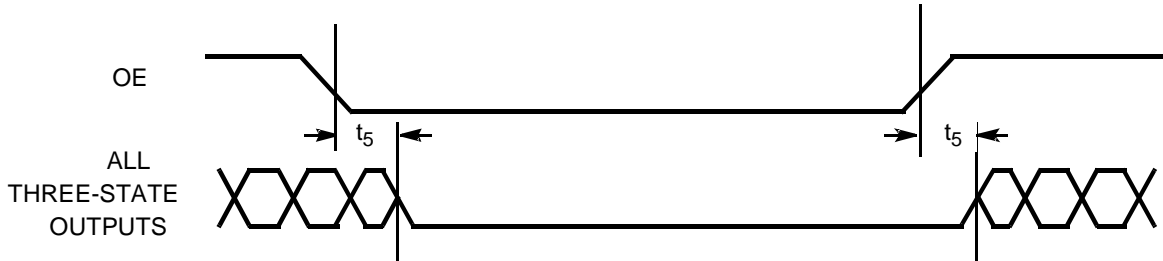
**Output Clock Switching Characteristics**

DESCRIPTION		CONDITIONS	MIN	TYP	MAX	UNIT
1/t <sub>1</sub>	Output Frequency	Clock output limit, CMOS, Commercial			200	MHz
t <sub>3</sub>	Rising Edge Slew Rate	Output clock rise time, 20% – 80% V <sub>dd</sub>	0.75	1.4		nS
t <sub>4</sub>	Falling Edge Slew Rate	Output clock fall time, 20% – 80% V <sub>dd</sub>	0.75	1.4		nS
t <sub>5</sub>	Output tri-state timing after SD/OE switches	Time for output to enter/leave tri-state mode		150	300	nS
t <sub>6</sub>	Clock Jitter measured at V <sub>dd</sub> /2	Peak-to-Peak period jitter, CLK outputs		200		pS

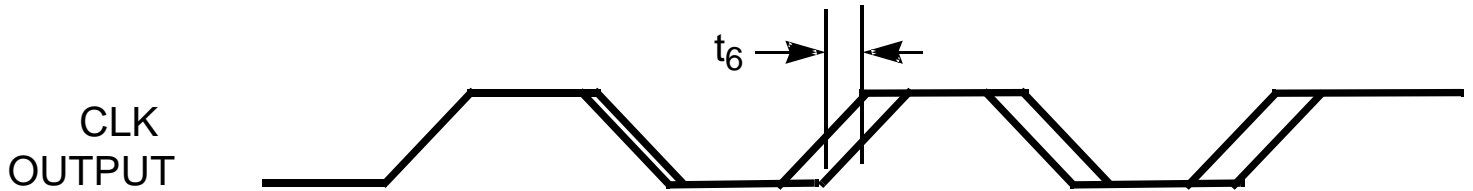
ALL OUTPUTS, DUTY CYCLE, RISE/FALL TIME



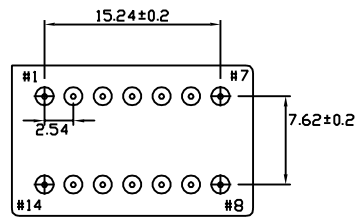
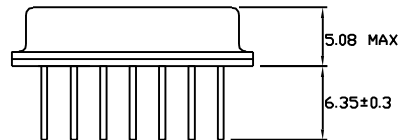
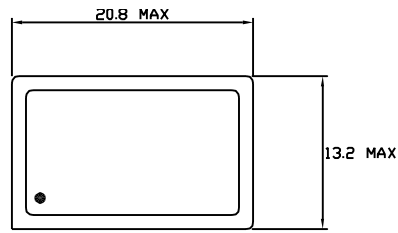
OUTPUT 3-STATE TIMING



CLK OUTPUT JITTER



**DIP**

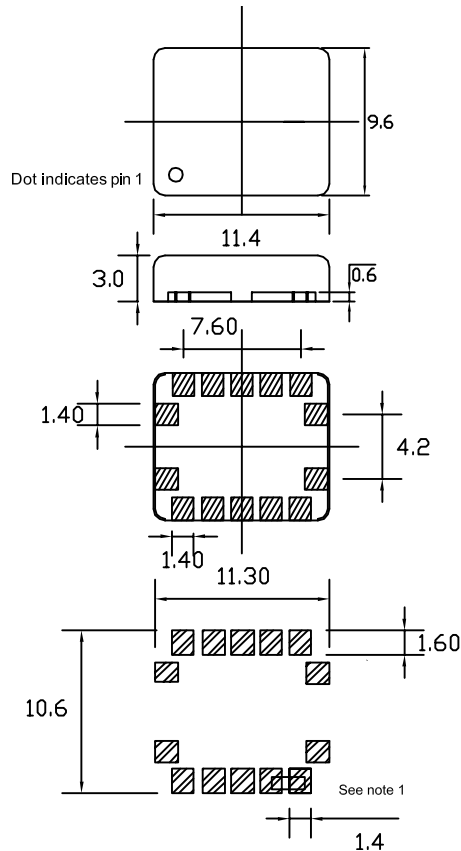


Dimensions are in mm

**PIN FUNCTION**

- PIN 1 OE (CONNECT TO VDD)
- PIN 2 SUSPEND (CONNECT TO GND)
- PIN 3 VDD
- PIN 4 CLK C OUTPUT
- PIN 5 CONNECT TO PIN 6
- PIN 6 CONNECT TO PIN 5
- PIN 7 GND
- PIN 8 FACTORY USE (MAKE NO CONNECTION)
- PIN 9 CLK D OUTPUT
- PIN10 FACTORY USE (MAKE NO CONNECTION)
- PIN 11 FACTORY USE (MAKE NO CONNECTION)
- PIN 12 FACTORY USE (MAKE NO CONNECTION)
- PIN 13 CLK A OUTPUT
- PIN 14 CLK B OUTPUT

**SMD**



**PIN FUNCTION**

- PIN 1 FACTORY USE (MAKE NO CONNECTION)
- PIN 2 OE
- PIN 3 VDD
- PIN 4 CLK C OUTPUT
- PIN 5 CONNECT TO PIN 6
- PIN 6 CONNECT TO PIN 5
- PIN 7 GND
- PIN 8 FACTORY USE (MAKE NO CONNECTION)
- PIN 9 CLK D OUTPUT
- PIN10 FACTORY USE (MAKE NO CONNECTION)
- PIN 11 FACTORY USE (MAKE NO CONNECTION)
- PIN 12 FACTORY USE (MAKE NO CONNECTION)
- PIN 13 CLK A OUTPUT
- PIN 14 CLK B OUTPUT

Dimensions in mm  
Recommended solder pad layout

Note1:  
For proper operation pin 5 must be connected to pin 6

